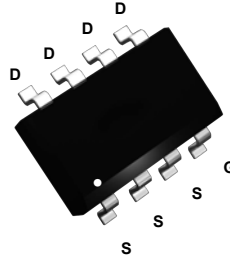
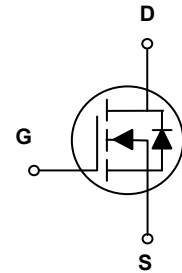


Main Product Characteristics

$V_{(BR)DSS}$	30V
$R_{DS(ON)}$	6.8m Ω (Max.)
I_D	20A



SOP-8



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFQ6R803 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-to-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current, @ Steady-State ($T_C=25^\circ\text{C}$)	I_D	20	A
Continuous Drain Current, @ Steady-State ($T_C=100^\circ\text{C}$)		13	A
Pulsed Drain Current ($T_C=25^\circ\text{C}$) ¹	I_{DM}	80	A
Power Dissipation ($T_C=25^\circ\text{C}$) ²	P_D	3.6	W
Single Pulse Current	I_{AS}	11.6	A
Single Pulse Avalanche Energy ⁵	E_{AS}	33.6	mJ
Junction-to-Case	$R_{\theta JC}$	35	$^\circ\text{C/W}$
Junction-to-Ambient (PCB Mounted, Steady-State)	$R_{\theta JA}$	62	$^\circ\text{C/W}$
Operating Junction and Storage Temperature Range	T_J/T_{STG}	-55 to +150	$^\circ\text{C}$
Soldering Temperature (SMD)	T_{SOLD}	260	$^\circ\text{C}$

Electrical Characteristics (T_A=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	30	-	-	V
Drain-to-Source Leakage Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V, T _J =25°C	-	-	1.0	μA
		V _{DS} =30V, V _{GS} =0V, T _J =125°C	-	2.0	-	
Gate-to-Source Forward Leakage	I _{GSS}	V _{DS} =0V, V _{GS} =± 20V	-	-	± 100	nA
Static Drain-to-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =10A	-	5.3	6.8	mΩ
		V _{GS} =4.5V, I _D =8A	-	7.7	10	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.1	-	2.5	V
Gate Resistance	R _g	f=1MHz	-	2.3	-	Ω
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =15V, f=1MHz	-	865	-	pF
Output Capacitance	C _{oss}		-	497	-	
Reverse transfer capacitance	C _{rss}		-	35	-	
Total Gate Charge ^{3,4}	Q _g		-	16.2	-	
Gate-to-Source Charge ^{3,4}	Q _{gs}	I _D =20A, V _{DD} =15V, V _{GS} =10V	-	3.4	-	
Gate-to-Drain("Miller") Charge ^{3,4}	Q _{gd}		-	2.3	-	
Gate-to- Plateau ^{3,4}	V _{plateau}		-	3.4	-	V
Turn-on Delay Time ^{3,4}	t _{d(on)}	V _{DD} =20V, V _{GS} =10V, R _G =3Ω, I _D =9A	-	4.4	-	nS
Rise Time ^{3,4}	t _r		-	31	-	
Turn-Off Delay Time ^{3,4}	t _{d(off)}		-	21	-	
Fall Time ^{3,4}	t _f		-	12	-	
Drain-Source Ratings and Characteristics						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current (Body Diode)	I _S	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	20	A
Diode Pulse Current	I _{S,pulse}		-	-	80	A
Diode Forward Voltage	V _{SD}	I _S =5A, V _{GS} =0V	-	-	1.4	V
Reverse Recovery Time ³	t _{rr}	I _S =2A, V _{GS} =0V, V _R =30V, dI _F /dt=100A/us	-	30	-	nS
Reverse Recovery Charge ³	Q _{rr}		-	15	-	nC

Notes:

- Pulse time of 5μs.
- The dissipated power value will change with the temperature. When it is greater than 25°C, the dissipated power value will decrease by 0.55°C/W for every 1 degree of temperature increase.
- Pulse Test: Pulse width ≤ 300μs, duty cycle ≤ 2%.
- Basically unaffected by operating temperature.
- L=0.5mH, R_G=25Ω, V_{DD}=24V, T_J=25°C.

Typical Electrical and Thermal Characteristic Curves

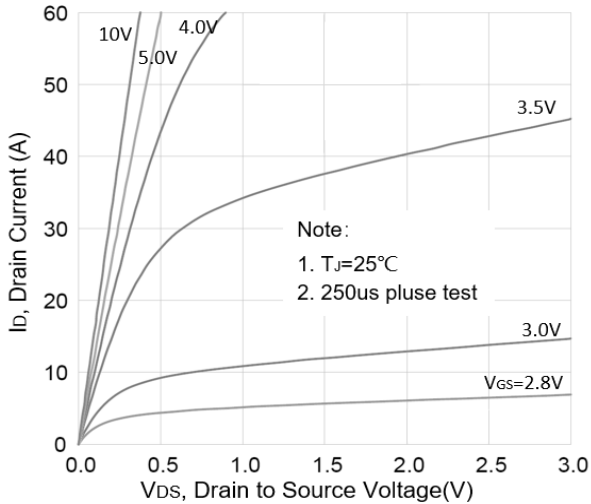


Figure1. Typical Output Characteristics

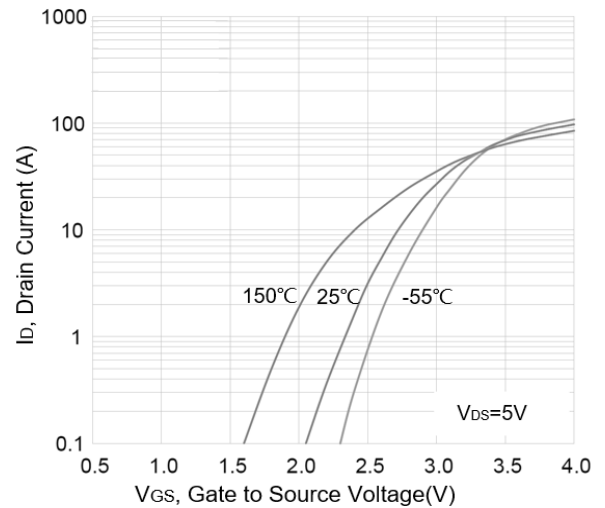


Figure2. Transfer Characteristics

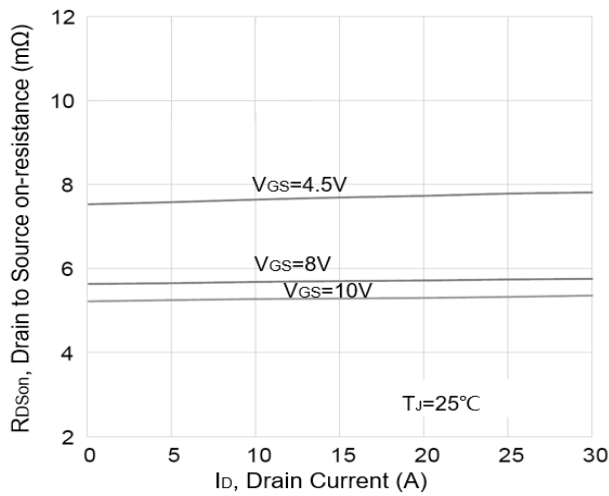


Figure3. Rds(on) vs. Drain Current

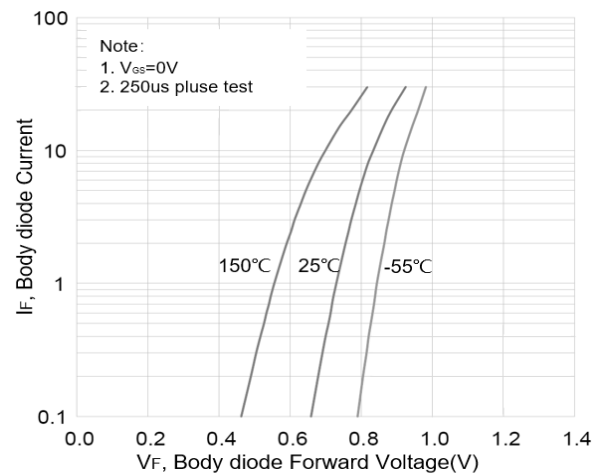


Figure4. Body Diode Characteristics

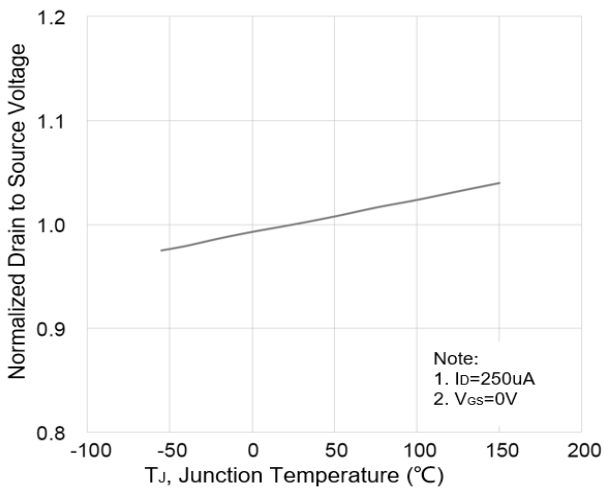


Figure5. Normalized BV_{dss} vs. T_J

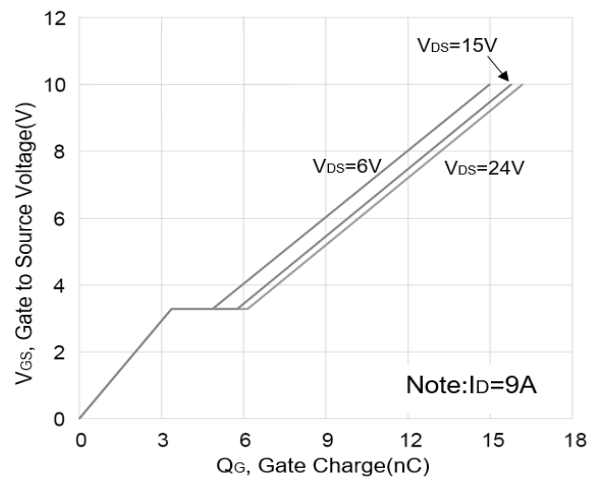


Figure6. Gate Charge

Typical Electrical and Thermal Characteristic Curves

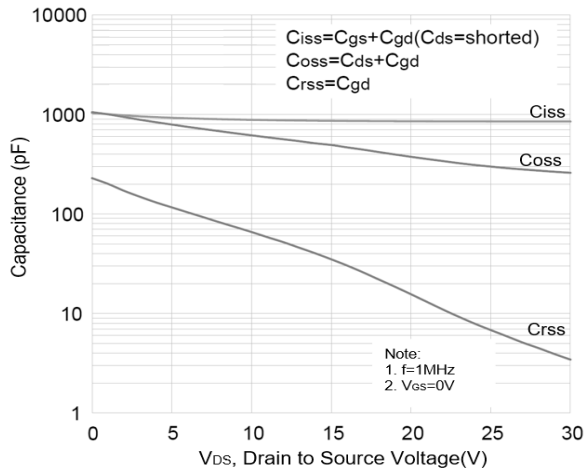


Figure7. Capacitance Characteristics

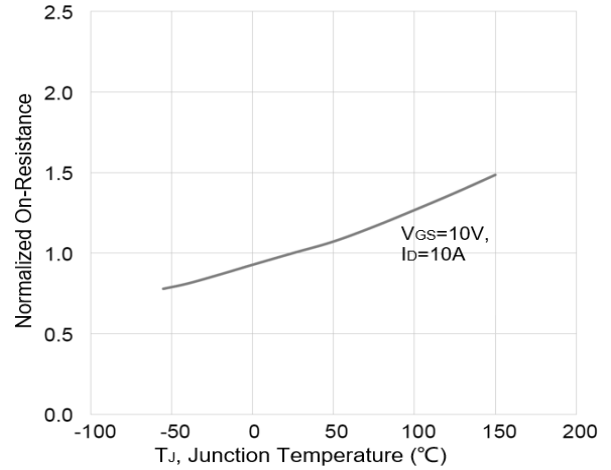


Figure8. Normalized R_{dson} vs. T_J

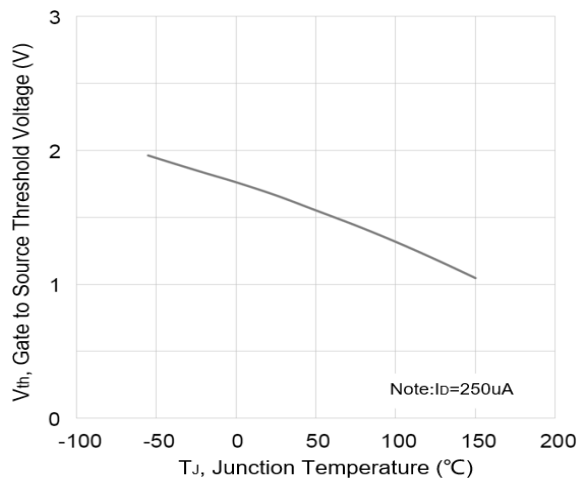


Figure9. Power Dissipation vs. T_J

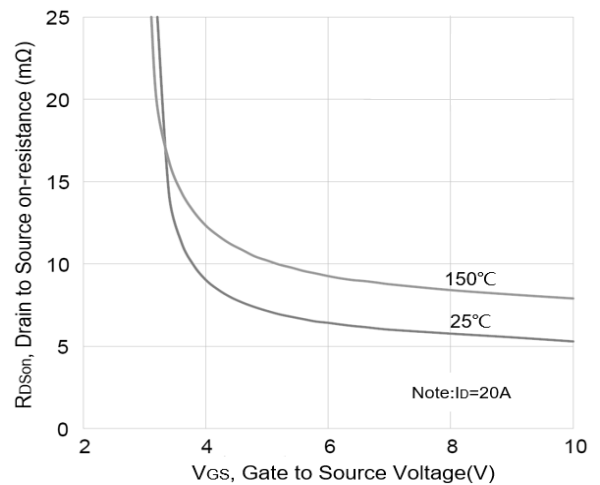
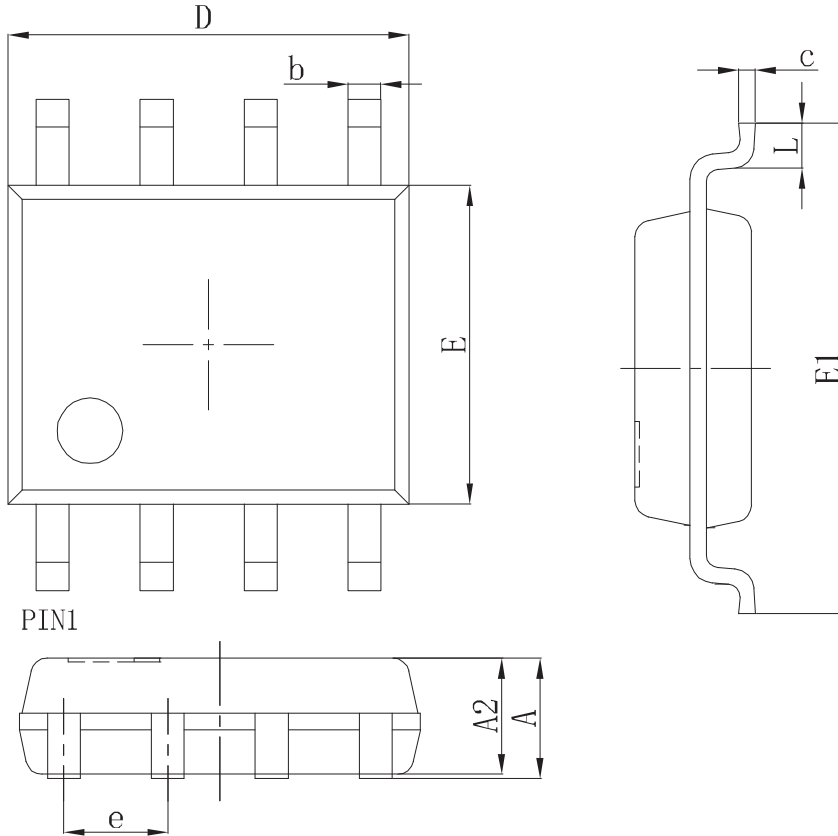


Figure10. R_{dson} vs. Gate to Source Voltage (V)

Package Outline Dimensions (SOP-8)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.30	1.70	0.051	0.067
A2	1.25	1.55	0.049	0.061
c	0.17	0.25	0.007	0.010
E	3.80	4.00	0.150	0.157
E1	5.80	6.20	0.228	0.244
L	0.45	0.75	0.018	0.030
b	0.33	0.51	0.013	0.020
D	4.80	5.00	0.189	0.197
e	1.27 BSC		0.050 BSC	

Order Information

Device	Package	Marking	Carrier	Quantity
GSFQ6R803	SOP-8	Q6R803	Tape & Reel	3,000 Pcs / Reel